

176

ABSTRACT

The present invention provides a curable composition providing a curing product having excellent adhesive properties and high transparency, or a curing product having high toughness and transparency.

A curable composition which contains (A) an organic compound containing at least two carbon-carbon double bonds reactive with a SiH group in each molecule, (B) a silicon compound having at least two SiH groups in each molecule, (C) a hydrosilylation catalyst, (D) a silane coupling agent and/or an epoxy group-containing compound, and (E) a silanol condensation catalyst. A light-emitting diode sealed with a curing product obtainable by curing said curable composition.

15

20

25

30

35